

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,014,552 B1
APPLICATION NO. : 09/899871
DATED : March 21, 2006
INVENTOR(S) : Collier et al.

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Claims:

Please add the following claims which were allowed during prosecution of the patent application, but were mistakenly omitted from the printed patent:

Claim 19. (original claim 10) The system of claim 1, wherein the spray element is adapted to be removed from the system.

Claim 20. (previously presented claim 23) A method for polishing multiple semiconductor topographies, comprising:

moving a polishing pad with respect to a semiconductor topography and a spray element;

polishing the semiconductor topography by positioning it against the moving polishing pad;

measuring an amount of matter adhered to the polishing pad subsequent to said polishing;

spraying a pressurized fluid from the spray element upon the polishing pad while moving the polishing pad, wherein said spraying is conducted based upon the amount of matter measured; and

removing matter adhered to the polishing pad.

Claim 21. (previously presented claim 24) The method of claim 20, further comprising polishing one or more additional topographies prior to said measuring.

Claim 22. (previously presented claim 22) The method of claim 14, wherein said spraying is conducted simultaneously with polishing one or more semiconductor topographies with the polishing system.

Claim 23. (original claim 28) The method of claim 21, further comprising applying a polishing fluid from a dispense component prior to said polishing.

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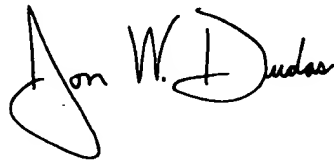
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 18

lines 22-23: please delete the text "and configured to move independent of an arm comprising the nozzles" since this phrase was not included in the claim when allowed.

Signed and Sealed this

Twenty-ninth Day of April, 2008

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a cursive "Dudas".

JON W. DUDAS
Director of the United States Patent and Trademark Office